



Special instruction: Keep bonding for Xin and Xout as close to die cavity edge as possible as we will mount additional 0201 component in red oval area.

Chip size: 1.10 × 1.30mm  
Chip thickness: 300 ± 30µm  
PAD size: 150µm × 100µm (VCC, OUT, OUTN pins)  
100µm × 100µm (excluding VCC, OUT, OUTN pins)  
Chip base: GND potential  
Note: The TEST pin is not used during normal operation.

**Instructions:**

- A. Standard process flow for die-attach and wire bond.  
B. Conductive silver paste 84-10MISR4 silver epoxy  
Ablestick is to be used for die attach.  
C. Curing: Curing time: 8 Hr  $\pm$  20 / - 0 min  
Curing temp: 160  $\pm$  10°C  
N2 Supply: 5 SCFH min.

Adhesive paste cure temperature is to be 160 degrees C for 8 hours minimum

D. Final assemblies to be nitrogen purged and vacuum packed for transportation. Trays used for shipping ceramic carriers are acceptable.

### Notes:

CF5036 and CF5037 use the same bonding diagram

Item ID	Description	Qty per Assembly
S5070DCK1	Sumitomo 6-pad 5x7mm pkg for NPC Differential output IC	1
CF5036D1-1	NPC IC	1
C0402K-103-PD	Capacitor 0402 0.01uF SMD	1

Revision	Date	Reason
A	2005/12/28	Update format for general publication
-	2005/11/23	Original Issue